~~WHAT IS CLAIMED IS:~~CLAIMS

1. A curable composition comprising a polymerizable material and an initiator, wherein
   the polymerizable material comprises a first monomer and a second monomer,
   the second monomer including a ring structure selected from a maleimide-ring, a pyrone ring, or a 2-furanone ring;
   the second monomer is soluble in the first monomer, and
   the curable composition has a viscosity of not greater than 10 mPa·s.
2. The curable composition of claim 1, wherein an amount the second monomer is at least 2 wt% and not greater than 20 wt% based on the total weight of the curable composition.
3. The curable composition of claim 1, wherein the second monomer includes a maleimide ring structure.
4. The curable composition of claim 3, wherein the second monomer includes N-benzylmaleimide (N-BMI); N-cyclohexylmaleimide (N-CMI); N-phenylmaleimide (N-PMI); bis(3-ethyl-5-methyl-4-maleimidophenyl)methane (BEMMI); or any combination thereof.
5. The curable composition of claim 1, wherein the first monomer includes an acrylate-monomer.
6. The curable composition of claim 5, wherein the acrylate monomer includes an aromatic group.
7. The curable composition of claim 6, wherein the acrylate monomer includes benzyl acrylate (BA); 1-naphthyl acrylate (1-NA); bisphenol A dimethacrylate (BPADMA); or any combination thereof.
8. The curable composition of claim 1, comprising at least one further monomer.
9. The curable composition of claim 1, wherein the at least one further monomer includes a substituted or unsubstituted divinyl benzene (DVB).
10. The curable composition of claim 9, wherein the polymerizable material comprises an aromatic acrylate monomer, a monomer including a maleimide ring, and a substituted or unsubstituted divinyl benzene (DVB).
11. ~~The curable composition of claim 1, wherein the curable composition is essentially free of a non-polymerizable solvent.~~

~~12.~~11. A laminate comprising a substrate and a cured layer overlying the substrate, wherein the cured layer ~~comprises an acrylate/maleimide copolymer~~is formed by applying a layer of the curable composition of claim 1 onto the substrate and curing the curable composition; wherein a total carbon content of the ~~at~~ cured layer is least 74 %, and a weight loss of the cured layer after a heat treatment at a temperature of 250°C for 90 seconds is not greater than 2.5% based on the total weight of the cured layer before the heat treatment.

~~13.~~12. The laminate of claim ~~12~~11, wherein the cured layer has a Storage Modulus of at least 4.5 GPa.

~~14. The laminate of claim 12, wherein the acrylate/maleimide copolymer further comprises divinyl benzene.~~

~~15.~~13. A method of manufacturing an article comprising:

applying a layer of a curable composition of claim 1 on a substrate~~, wherein the curable composition comprises a polymerizable material and a photoinitiator, and wherein the polymerizable material comprises a first monomer and a second monomer, the second monomer including a ring structure selected from a maleimide ring, a pyrone ring, or a 2-furanone ring; the second monomer is soluble in the first monomer; and the curable composition has a viscosity of not greater than 10 mPa·s~~;

bringing the curable composition into contact with a superstrate;

curing the curable composition with light or heat to form a cured layer;

removing the superstrate from the cured layer; and

processing the substrate with the cured layer to make the article.

~~16.~~14. The method of claim ~~15~~13, wherein curing comprises a conversion of at least 65% of all double bonds contained in the polymerizable material within 10 seconds.

~~17. The method of claim 15, wherein the polymerizable material includes an acrylate monomer as the first monomer and a monomer including a maleimide ring as the second monomer type.~~

~~18. The method of claim 15, wherein the polymerizable material includes at least one further monomer.~~

~~19. The method of claim 18, wherein the at least one further monomer is substituted or unsubstituted divinyl benzene.~~

~~20.~~15. The method of claim ~~15~~13, wherein the cured layer has a weight loss after a heat treatment at a temperature of 250°C for 90 seconds of not greater than 2.5% based on the total weight of the cured layer.